



RS1001FL~RS1008FL

SMALL SURFACE MOUNT FAST DIODES

VOLTAGE 100 to 800 Volts

CURRENT

1.0 Amperes

SOD-123FL

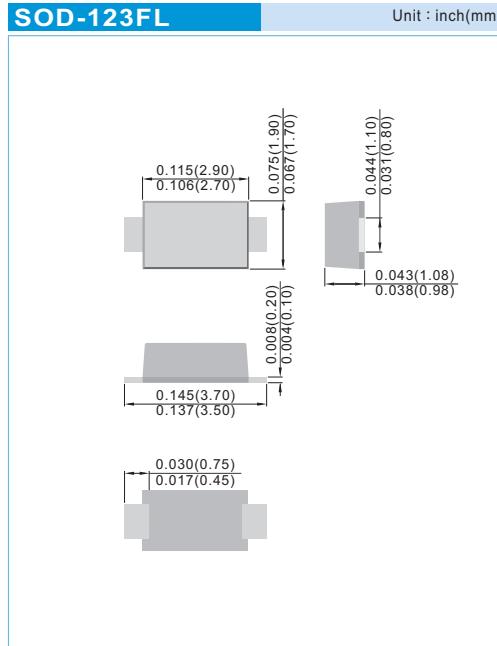
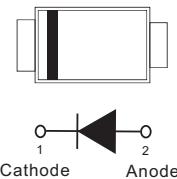
Unit : inch(mm)

FEATURES

- For surface mounted applications
- Low profile package
- Ideal for automated placement
- Glass Passivated Chip Junction
- High temperature soldering : 260°C / 10 seconds at terminals
- Lead free in comply with EU RoHS 2002/95/EC directives.
- Green molding compound as per IEC61249 Std. . (Halogen Free)

MECHANICAL DATA

- Case : JEDEC SOD-123FL, Molded plastic over passivated junction
- Terminals : Solderable per MIL-STD-750, Method 2026
- Standard Packaging : 8mm tape (EIA-481)
- Apporx. Weight: 0.0006 ounces, 0.0173 grams
- Polarity : Color band cathode



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Rating	Test condition	Symbol	RS1001FL	RS1002FL	RS1004FL	RS1006FL	RS1008FL	Units
Marking Code		-	R1B	R1D	R1G	R1J	R1K	-
Maximum repetitive peak reverse voltage		V_{RRM}	100	200	400	600	800	V
Maximum RMS voltage		V_{RMS}	70	140	280	420	560	V
Maximum DC blocking voltage		V_{DC}	100	200	400	600	800	V
Maximum average forward rectified current Derate above $T_c=110^\circ\text{C}$		$I_{F(AV)}$	1.0					A
Maximum instantaneous forward voltage	0.7A 1.0A	V_F	1.15 1.3					V
Peak Forward Surge Current : 8.3ms single half sine-wave superimposed on rated load (JEDEC method)		I_{FSM}	30					A
Maximum DC reverse current at rated DC blocking voltage	$T_J=25^\circ\text{C}$ $T_J=125^\circ\text{C}$	I_R	1.0 50					μA
Typical capacitance	4V,1MHz	C_J	9					pF
Reverse recovery time	$I_F=0.5\text{A}$ $I_R=1\text{A}$ $I_{rr}=0.25\text{A}$	t_{rr}	150		250	500	nS	
Thermal resistance junction to ambient air		$R_{\theta JA}$	180					$^\circ\text{C/W}$
Operating junction and storage temperature range		T_J, T_{STG}	-55 to +150					$^\circ\text{C}$